



SSC8K23GN2

P-Channel Enhancement Mode MOSFET with Schottky Diode

➤ Features

P-Channel

VDS	VGS	RDSON Typ.	ID
-20V	±8V	135mΩ@-4V5	-2A
		180mΩ@-2V5	
		240mΩ@-1V8	

Schottky

VR	IR	VF Typ.	IO
20V	15uA	410mV @0.5A	1A

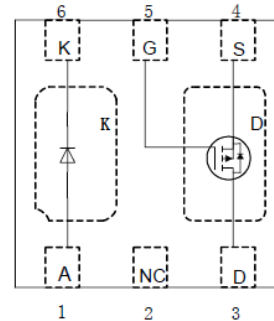
➤ Description

SSC8K23GN2 combines a P-Channel enhancement mode power MOSFET which is produced with high cell density and DMOS trench technology and a low forward voltage Schottky diode. The tiny and thin outline saves PCB consumption.

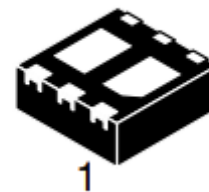
➤ Applications

- Li-Battery Charging
- High Side DC/DC Converter
- High Side Driver for Brushless DC motor
- Power Management in Portable, Battery Powered Devices

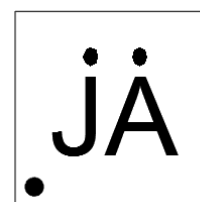
➤ Pin configuration



Top View



Bottom View



Marking

➤ Ordering Information

Device	Package	Shipping
SSC8K23GN2	DFN2X2	3000/Reel



➤ **Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
P-MOS			
V_{DSS}	Drain-to-Source Voltage	-20	V
V_{GSS}	Gate-to-Source Voltage	± 8	V
I_D	Continuous Drain Current	-2	A
I_{DM}	Pulsed Drain Current	-8	A
Schottky Diode			
V_R	Schottky Reverse Voltage	20	V
I_F	Schottky Continuous Forward Current	1	A
Power Dissipation and Temperature			
P_D	Power Dissipation	1.1	W
T_J	Operation junction temperature	-55 to 150	$^{\circ}\text{C}$
T_{STG}	Storage temperature range	-55 to 150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance	115	$^{\circ}\text{C}/\text{W}$

➤ **Electronics Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise noted)**

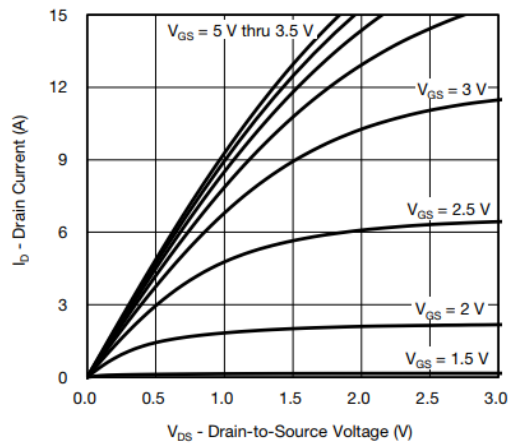
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
Schottky						
B_V	Reverse Breakdown Voltage	$I_R=100\mu\text{A}$	20			V
V_F	Forward Voltage Drop	$I_F=0.5\text{A}$		0.41	0.49	V
I_R	Maximum reverse leakage current	$V_R=20\text{V}$		15	200	μA



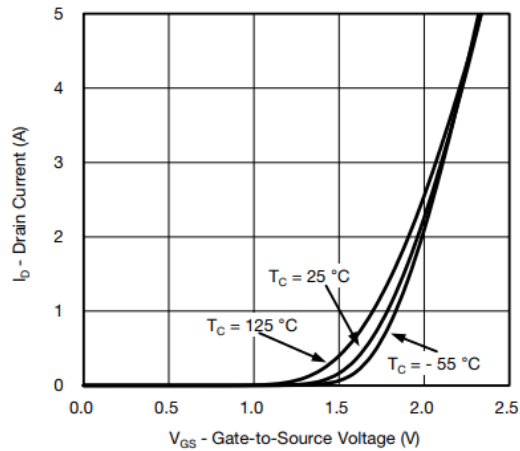
Symbol	Parameter	Test Conditions	Min	Typ.	Max	Unit
P-Channel Enhancement Mode MOSFET						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V$, $I_D=-250\mu A$	-20			V
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu A$	-0.5	-0.7	-1.2	V
$R_{DS(on)}$	Drain-Source On- Resistance	$V_{GS}=-4.5V$, $I_D=-1A$		135	190	m Ω
		$V_{GS}=-2.5V$, $I_D=-1A$		180	250	
		$V_{GS}=-1.8V$, $I_D=-1A$		240	500	
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-20V$, $V_{GS}=0V$			-1	μA
I_{GSS}	Gate-Source leak current	$V_{GS}=\pm 8V$, $V_{DS}=0V$			± 100	nA
G_{FS}	Transconductance	$V_{DS}=-10V$, $I_D=-1.7A$		7.1		S
V_{SD}	Forward Voltage	$V_{GS}=0V$, $I_S=-1A$			1.3	V
C_{iss}	Input Capacitance	$V_{DS}=-10V$, $V_{GS}=0V$, $f=1MHz$		450		pF
C_{oss}	Output Capacitance			180		
C_{rss}	Reverse Transfer Capacitance			90		
$T_{D(ON)}$	Turn-on delay time	$V_{DS}=-6V$, $V_{GS}=-4.5V$, $R_L=6R$, $R_G=6R$, $I_D=-1A$		20		ns
T_r	Turn-on rise time			30		
$T_{D(OFF)}$	Turn-off delay time			180		
T_f	Turn-off fall time			120		



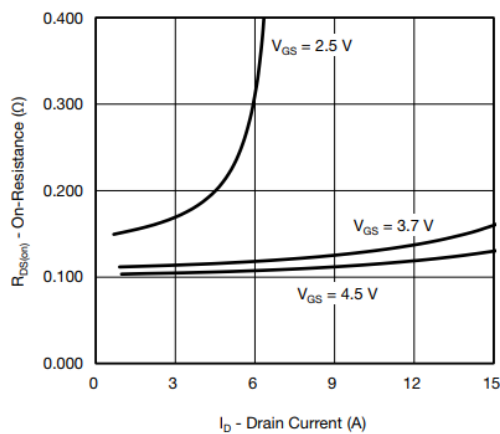
➤ Typical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted)



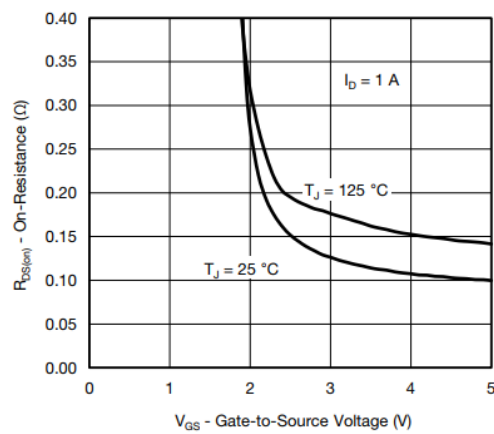
Output Characteristics



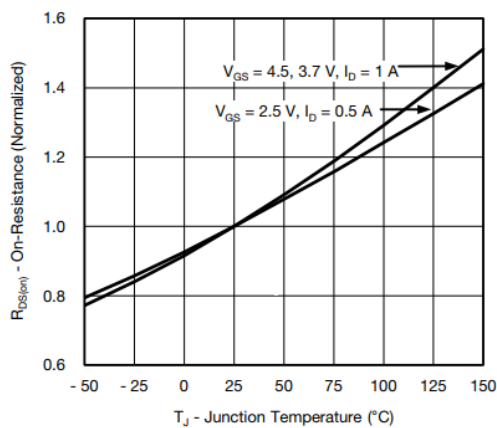
Transfer Characteristics



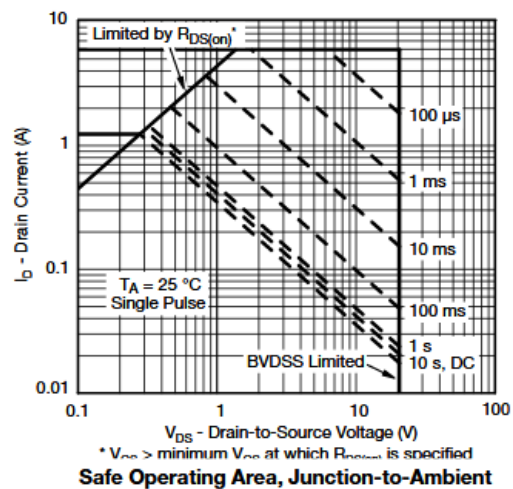
On-Resistance vs. Drain Current and Gate Voltage



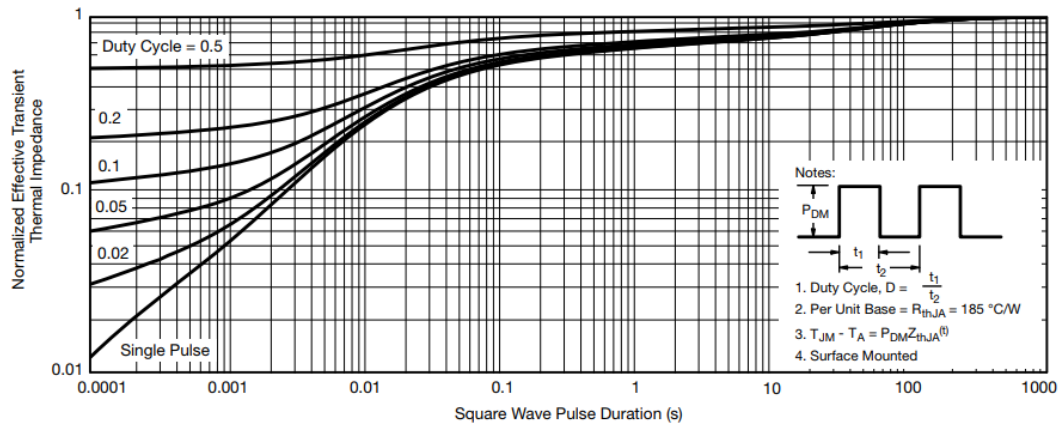
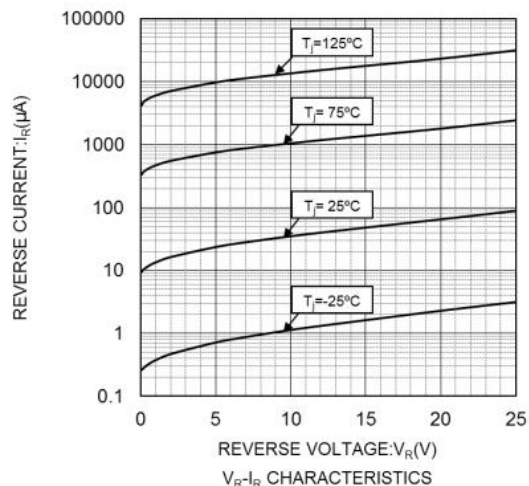
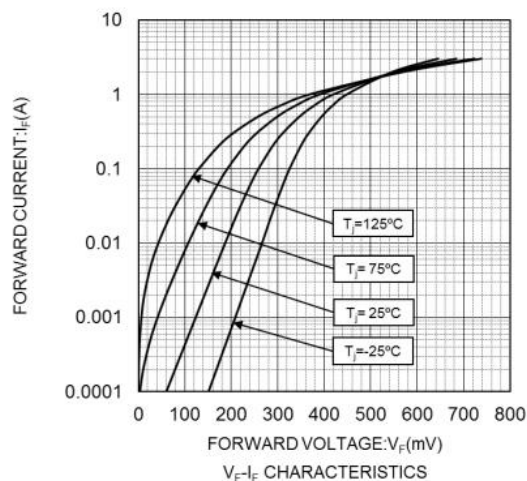
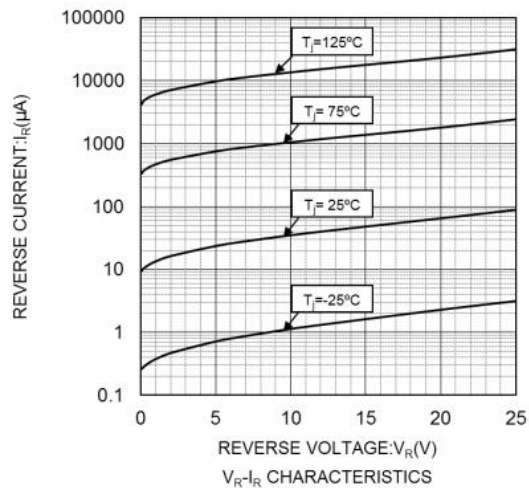
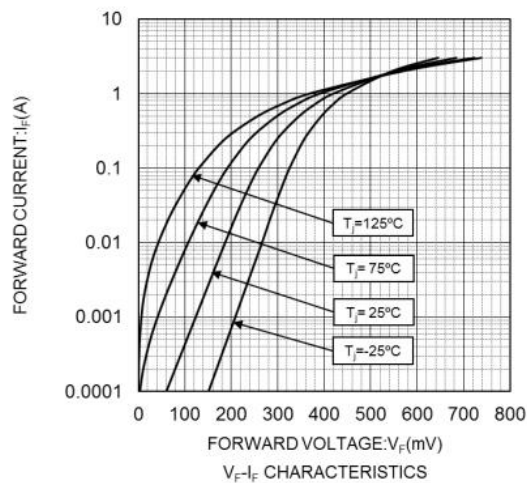
On-Resistance vs. Gate-to-Source Voltage



On-Resistance vs. Junction Temperature

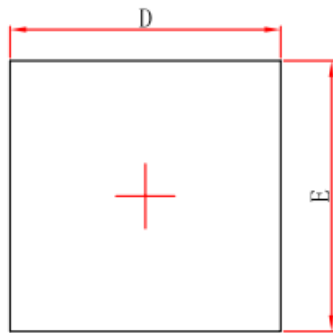


Safe Operating Area, Junction-to-Ambient

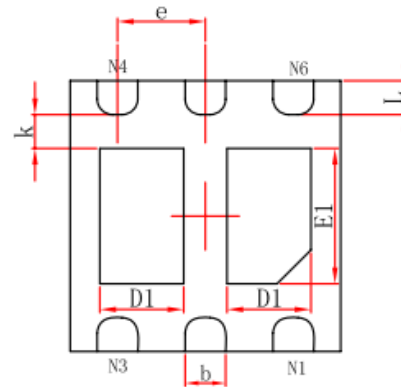
**Normalized Thermal Transient Impedance, Junction-to-Ambient**



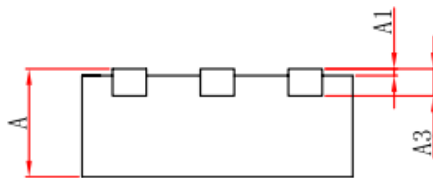
➤ Package Information



Top View



Bottom View



Side View

DFN2X2-6L

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	1.924	2.076	0.076	0.082
D1	0.520	0.720	0.020	0.028
E1	0.900	1.100	0.035	0.043
k	0.200MIN.		0.008MIN.	
b	0.250	0.350	0.010	0.014
e	0.650TYP.		0.026TYP.	
L	0.174	0.326	0.007	0.013

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